### S1C17 Family Technical Manual Errata

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<th>Pad/Bump Configuration</th>
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(Error)
- Chip size X = 2.637 mm, Y = 2.543 mm
- Pad opening No. 1 to 17, 37 to 47: X = 76 μm, Y = 85 μm
  No. 18 to 36, 48 to 67: X = 85 μm, Y = 76 μm
  Bump size No. 1 to 17, 37 to 47: X = 70 μm, Y = 79 μm
  No. 18 to 36, 48 to 67: X = 79 μm, Y = 70 μm
- Chip thickness 400 μm

(Correct)
- Chip size X = 2.637 mm, Y = 2.543 mm
- Pad opening No. 1 to 17, 37 to 47: X = 76 μm, Y = 85 μm
  No. 18 to 36, 48 to 67: X = 85 μm, Y = 76 μm
  Bump size No. 1 to 17, 37 to 47: X = 70 μm, Y = 79 μm
  No. 18 to 36, 48 to 67: X = 79 μm, Y = 70 μm
- Chip thickness 400 μm
- Alignment mark:  Upper left (X:-1206.1um, Y:1159.1um)  Lower right(X:1206.1um, Y:-1095.1um)